100 V, 3.0 A, Low V_{CE(sat)} NPN Transistor

ON Semiconductor's e^2 PowerEdge family of low $V_{CE(sat)}$ transistors are surface mount devices featuring ultra low saturation voltage ($V_{CE(sat)}$) and high current gain capability. These are designed for use in low voltage, high speed switching applications where affordable efficient energy control is important.

Typical applications are DC-DC converters and power management in portable and battery powered products such as cellular and cordless phones, PDAs, computers, printers, digital cameras and MP3 players. Other applications are low voltage motor controls in mass storage products such as disc drives and tape drives. In the automotive industry they can be used in air bag deployment and in the instrument cluster. The high current gain allows e²PowerEdge devices to be driven directly from PMU's control outputs, and the Linear Gain (Beta) makes them ideal components in analog amplifiers.

Features

- These Devices are Pb-Free and are RoHS Compliant
- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable

MAXIMUM RATINGS $(T_A = 25^{\circ}C)$

Rating	Symbol	Max	Unit
Collector-Base Voltage	V_{CBO}	140	Vdc
Collector-Emitter Voltage	V_{CEO}	100	Vdc
Emitter-Base Voltage	V_{EB}	6.0	Vdc
Collector Current – Continuous – Peak	I _C	3.0 6.0	Adc
Base Current	I _B	0.5	Adc
Total Power Dissipation @ T _C = 25°C Derate above 25°C	P _D	12.5 0.1	W W/°C
Total Power Dissipation (Note 1) @ T _A = 25°C Derate above 25°C	P _D	1.4 0.011	W W/°C
Operating and Storage Junction Temperature Range	T _J , T _{stg}	-65 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

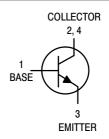
 These ratings are applicable when surface mounted on the minimum pad sizes recommended.



ON Semiconductor®

http://onsemi.com

100 VOLTS, 3.0 AMPS 12.5 WATTS NPN LOW $V_{CE(sat)}$ TRANSISTOR





DPAK CASE 369C STYLE 1

MARKING DIAGRAM



Y = Year WW = Work Week 1C31E = Device Code G = Pb-Free

ORDERING INFORMATION

Device	Package	Shipping [†]
NSS1C301ET4G	DPAK (Pb-Free)	2500/ Tape & Reel
NSV1C301ET4G	DPAK (Pb-Free)	2500/ Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{ heta JC}$	10	°C/W
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{ heta JA}$	89.3	°C/W

^{2.} These ratings are applicable when surface mounted on the minimum pad sizes recommended.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS					
Collector – Emitter Breakdown Voltage ($I_C = 10 \text{ mA}, I_B = 0$)	V _{(BR)CEO}	100			V
Collector – Base Breakdown Voltage (I _C = 0.1 mA, I _E = 0)	V _{(BR)CBO}	140			V
Emitter – Base Breakdown Voltage ($I_E = 0.1 \text{ mA}, I_C = 0$)	V _{(BR)EBO}	6.0			V
Collector Cutoff Current (V _{CB} = 140 V, I _E = 0)	I _{CBO}			0.1	μΑ
Emitter Cutoff Current (V _{EB} = 6.0 V)	I _{EBO}			0.1	μΑ
ON CHARACTERISTICS					
DC Current Gain (Note 3) $ \begin{aligned} &(I_C = 0.1 \text{ A, } V_{CE} = 2.0 \text{ V}) \\ &(I_C = 0.5 \text{ A, } V_{CE} = 2.0 \text{ V}) \\ &(I_C = 1.0 \text{ A, } V_{CE} = 2.0 \text{ V}) \\ &(I_C = 3.0 \text{ A, } V_{CE} = 2.0 \text{ V}) \end{aligned} $	h _{FE}	200 200 120 80		360	
Collector – Emitter Saturation Voltage (Note 3) ($I_C = 0.1 \text{ A}, I_B = 10 \text{ mA}$) ($I_C = 1.0 \text{ A}, I_B = 0.100 \text{ A}$) ($I_C = 2.0 \text{ A}, I_B = 0.200 \text{ A}$) ($I_C = 3.0 \text{ A}, I_B = 0.300 \text{ A}$)	V _{CE(sat)}		0.015 0.045 0.080 0.115	0.050 0.090 0.150 0.250	V
Base – Emitter Saturation Voltage (Note 3) $(I_C = 1.0 \text{ A}, I_B = 0.1 \text{ A})$	V _{BE(sat)}			1.0	V
Base – Emitter Turn–on Voltage (Note 3) (I _C = 1.0 A, V _{CE} = 2.0 V)	V _{BE(on)}			0.90	V
Cutoff Frequency (I _C = 500 mA, V _{CE} = 10 V, f = 100 MHz)	f _T		120		MHz
Input Capacitance (V _{EB} = 5.0 V, f = 1.0 MHz)	Cibo		360		pF
Output Capacitance (V _{CB} = 10 V, f = 1.0 MHz)	Cobo		30		pF

^{3.} Pulsed Condition: Pulse Width = 300 msec, Duty Cycle \leq 2%.

TYPICAL CHARACTERISTICS

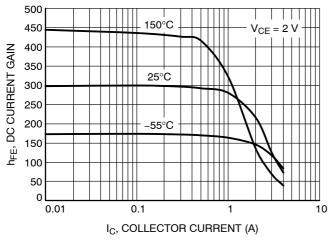


Figure 1. DC Current Gain

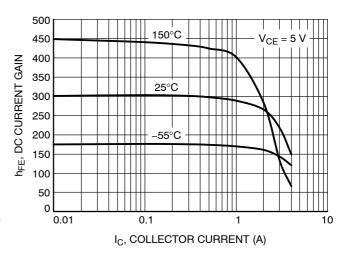


Figure 2. DC Current Gain

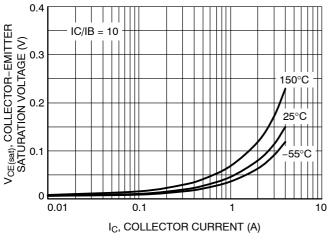


Figure 3. Collector–Emitter Saturation Voltage

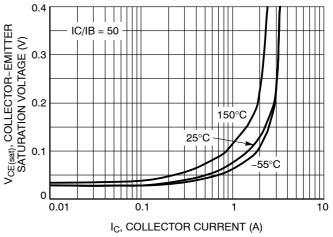


Figure 4. Collector–Emitter Saturation Voltage

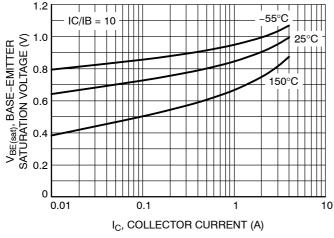


Figure 5. Base-Emitter Saturation Voltage

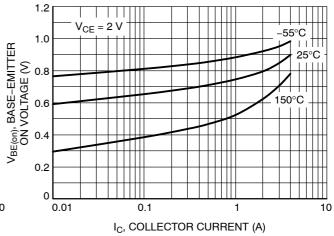


Figure 6. Base-Emitter "On" Voltage

TYPICAL CHARACTERISTICS

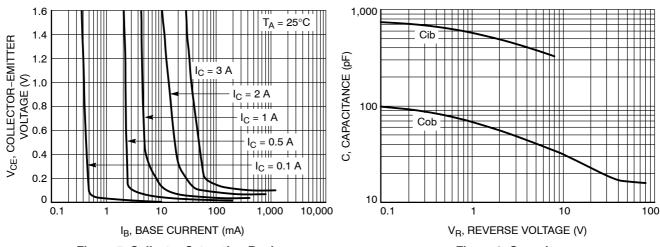


Figure 7. Collector Saturation Region

Figure 8. Capacitance

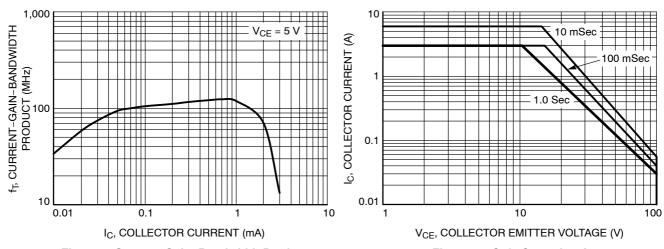


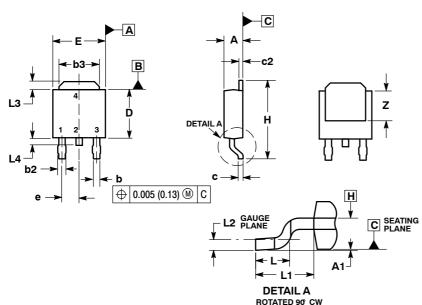
Figure 9. Current-Gain-Bandwidth Product

Figure 10. Safe Operating Area

PACKAGE DIMENSIONS

DPAK (SINGLE GAUGE)

CASE 369C ISSUE D



NOTES

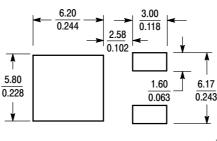
- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. CONTROLLING DIMENSION: INCHES.
- THERMAL PAD CONTOUR OPTIONAL WITHIN DI-MENSIONS b3, L3 and Z.
- DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
- DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
- DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.

	INC	HES	MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.086	0.094	2.18	2.38	
A1	0.000	0.005	0.00	0.13	
b	0.025	0.035	0.63	0.89	
b2	0.030	0.045	0.76	1.14	
b3	0.180	0.215	4.57	5.46	
С	0.018	0.024	0.46	0.61	
c2	0.018	0.024	0.46	0.61	
D	0.235	0.245	5.97	6.22	
Е	0.250	0.265	6.35	6.73	
е	0.090	BSC	2.29	BSC	
Н	0.370	0.410	9.40	10.41	
L	0.055	0.070	1.40	1.78	
L1	0.108 REF		2.74 REF		
L2	0.020	BSC	0.51	BSC	
L3	0.035	0.050	0.89	1.27	
L4		0.040		1.01	
Z	0.155		3.93		

STYLE 1:

- PIN 1. BASE 2. COLLECTOR
 - EMITTER 4. COLLECTOR

SOLDERING FOOTPRINT*



(mm inches SCALE 3:1

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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